行政院國家科學委員會專題研究計畫 成果報告

以動態觀點為基準的生產規化：重複製程(3/3)
研究成果報告(完整版)

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計 畫 主 持 人 ：余政靖

計畫參與人員：博士班研究生-兼任助理：蘇安治、程建凱
碩士班研究生-兼任助理：李柏齊、陳晉仕
博士後研究：J. Ward

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行政院國家科學委員會補助專題研究計畫 ■ 成果報告
□期中進度報告

以動態觀點為基準的生產規化：重複製程(3/3)

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計畫主持人： 余政靖　國立台灣大學化工系
共同主持人：
計畫參與人員： 蘇安治　國立台灣大學化工系

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行政院國家科學委員會專題研究計畫成果報告

以動態觀點為基準的生產規化：重複製程(3/3)

Batch Process Monitoring Using Key Sensitivity Index

計畫編號：NSC 95-2221-E-002-266

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主持人：余政靖　　　　國立台灣大學化工系

計畫參與人員：蘇安治　　國立台灣大學化工系

Abstract

Process monitoring is essential to maintain product quality in semiconductor manufacturing and the batch-wise processing nature makes data-based monitoring attractive. However, unlike chemical processes, the semiconductor manufacturing process exhibits the following characteristics: (1) much shorter (minutes) and often variable (deliberately adjusted) batch time, (2) multiple processing steps (10-20) in each batch, (3) only some particular processing steps (not the entire trajectory) constituting the quality determining steps, (4) mixed products for the same batch processing. In this work, instead of incorporating large number of trajectory data with variable batch time and possibly "missing" data for some process variables using multivariate statistics, a process-insight based approach, key sensitive index (KSI), is taken. From process knowledge, the key sensitive time-slot (KST) in the recipe is identified. Next, possible key sensitive process variables (KSV) are selected and validated according to the process trend correlation. Then, an index for these variables (key sensitive index, KSI) is sought. The KSI's can be classified into: variable-based, model-based, and data-based measures. Two integrated circuit processing examples from real fab data are used to illustrate the KSI-based approach and results clearly indicate that process trend is captured using KSI-based approach.

1、Introduction

Batch processes play an important role in the production and processing of chemicals, pharmaceutical, and semiconductor devices. Generally, a batch process is characterized by prescribed processing of raw materials for a finite duration to convert them to products. A high degree of reproducibility is necessary to obtain successful batches. Some batch processes include a single step, whereas many others are carried out in a sequence of discrete steps, which are usually referred as recipes in semiconductor manufacturing. Events taking place in each step have impacts on the final product yield and quality. For chemical process industry (CPI), upon completion of a batch, a range of quality measurements is usually made at the quality control laboratory, often hours later. For semiconductor industry, the quality measurements are usually not available at the end of a single processing unit until the processes in several processing units have been completed. Therefore, monitoring and control of the intermediate stages of operation and intermediate product quality is as important as monitoring and control at the final stage.

Online process performance monitoring and product quality prediction in real time can reduce quality variations. Multivariate statistical projection methods such as principal component analysis (PCA) and partial least squares (PLS) are capable of utilizing massive amounts of process data and compress the information data down into a lower dimensional latent space in which process monitoring and results interpreting are much easier. These methods are first utilized in developing multivariate statistical process monitoring and quality prediction techniques for continuous processes (Kourti et al., 1996). Nomikos and MacGregor (1994) pioneer the use of the large number of trajectory measurements collected from batch process and develop multi-way projection methods for statistical process monitoring. Batch data are recorded in terms of batch runs, variables, and time. They are arranged into a three-dimensional array in the multi-way projection methods and, therefore, analysis of batch processes data arouses a variety of challenges. Due to the nature of batch processes, every batch may come to completion at a different termination time, resulting in unequal batch data lengths. The unequal length batch data should be equalized prior to forming a three-dimensional array. The simplest way for equalizing batch lengths is cutting batch data lengths to the length of the variable with the shortest sequence, but this is not recommended because of the possible significant information loss generated by discarding data. Several methods for equalizing batch lengths, such as the indicator variable technique (IVT) (Nomikos and MacGregor, 1995; Neogi and Schlags, 1998), dynamic time warping (DTW) (Kassidas et al., 1998), and curve registration (Williams and Cinar, 2000), have been suggested in the literature. IVT is based on selecting a process variable to indicate the progress of the batch instead of the time axis. This variable should be chosen such that it progresses monotonically in time and has the same starting and ending value for each batch. But IVT does not account for the locations and the alignment of critical local features (landmarks) of each trajectory. DTW is used to synchronize two trajectories by appropriately translating, expanding, and contracting localized segments within the trajectories to achieve a minimum distance between the two trajectories. However, warping the batch trajectories to have the minimum distance with the reference batch trajectory may distort their critical features or fault patterns and, hence, reduce the monitoring ability. Curve registration is a two-step process of identifying landmarks within a trajectory (or set of trajectories) and then warping the test trajectory to the reference trajectory containing reference landmarks. Identifying multivariate landmarks is challenging because the number and location of landmarks may be different for different process variables. In addition to unequal batch data lengths, another

difficulty for implementing multi-way projection methods is that the process variables are not necessarily recorded at regular intervals. Thus, interpolation is often needed to find measurements at regular time instances. This has to be done properly; otherwise, the auto-correlation and cross-correlation might be seriously affected (Kourti, 2003).

Multi-way PCA (MPCA) has been successfully applied for batch process analyses and monitoring in chemical process industry (e.g. Nomikos and MacGregor, 1995, MacGregor and Kourti, 1995). However, implementing multi-way PCA in the field of semiconductor manufacturing will encounter some difficulties. The main reason is that, unlike chemical processes, the IC processing has much shorter (seconds-minutes for a wafer as opposed to minutes-hours for chemicals) time duration. Preprocessing and arrangement of process data to deal with the problem of unequal batch data lengths using aforementioned methods will impose a relatively high computational burden and may significantly distort the critical features in the batch trajectories. Moreover, not the entire batch trajectory, but some particular processing sequence constitutes the quality determining steps, and this is especially true for crystallization processes in CPI and thermal processes in IC industries. Using the entire batch trajectory for analyses might cloud the relationship between variables in these critical steps and the final product quality and, subsequently, reduces the resolution in process trend monitoring. These characteristics make the data-based approaches difficult in semiconductor manufacturing industry.

In this work, an alternative for batch process monitoring is sought. Instead of incorporating large number of trajectory data with variable batch time and possibly "missing" data for some process variables using MPCA, a key sensitive index (KSI) based approach is proposed. From process insight or the experience of a process operator, a certain period time within a batch where measurements have significant effects on product quality, the key sensitive time-slot (KST), is identified. Next, based on the KST, possible key sensitive process variables (KSV) are chosen. The KSV may not be measured values themselves in KST, but some quantity, such as area, slope, maximum, etc., computed from the raw measurements. Once a KSV is computed from each batch (wafer-to-wafer) under normal operation, its autocorrelation function is calculated as the batch process progresses. If significant autocorrelation is found, a time-series model could be established from the selected KSV; if not, a different KSV is sought. With the time-series model, the process trend can thus be forecasted and the index for process operating status (key sensitive index, KSI) is defined and computed. By monitoring the KSI, possible maintenance action can therefore be called for, whenever necessary. This provides dynamical capability for process trend monitoring while maintaining the simplicity of single-variate analyses, if applicable. Two IC processing examples are used to illustrate the KSI-based approach.

2、Key Sensitive Time-Slot And Key Sensitive Variables

2.1 Key sensitive time-slot (KST)

In one process tool, there are many measurements,

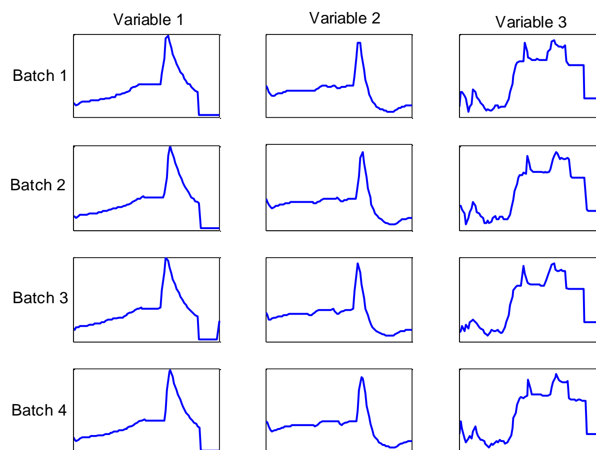


Fig. 1. Sketch of general process raw data in semiconductor manufacturing.

such as temperature, pressure, composition, flow rate, RF power etc., which will be acquired into database systems. Many engineers elaborate on mining useful knowledge or information from this huge amount of data. Figure 1 shows a simplified version of typical process raw data in semiconductor manufacturing. Because of the batch process characteristic, the techniques of process/equipment monitoring usually treats the data as three dimensions: batches, measurements, and time. Consequently, the multi-way PCA could be applied onto expanded 2-D data (Qin et al., 2005). When fetching raw data of a process tool, there are 10-90 available measured variables (depend on equipment). Many variables could be excluded because of the constant behavior or little influence on qualities from engineer's experience. It is the first step for dimension reduction and also the most important step to earn successful data analyses.

Despite of many successful applications of MPCA, several factors may impose difficulties in applications. First, the step length of each batch might be different. It results from that the operation time between batches is not coincident and this is quite true in tool level operation in IC processing. Second, the sampling interval may be different, and it leads to asynchronous data sequences. Third, it always encounters a problem about missing data, outlier, or other miscellanea when one does the data analysis. These difficulties naturally require substantial engineering effort on data pre-processing, to satisfy the argument format of modeling algorithms. In the worst case scenario, with excessive engineering effort, it may be not easy to restore the true system behavior.

After the selection of important measured variables, the next step is to cut each operation steps and filter them out. In practice, there are also many operation steps, typically 10-20, in a recipe (i.e., the entire batch run). Some steps are considered as pre-treatment, e.g., warming-up, introducing gas flows, etc., until the chamber condition is stabilized for subsequent processing. These kinds of minor steps could be neglected. The key sensitive time-slot is defined as the steps that have significant influence on quality or healthy condition such as the thermal budget period in RTP or particles-generation related steps in etching processes. For example, there are 6 steps in Fig.2, but only 3 critical steps, B, D, and F which are key sensitive time-slots. Usually, KSTs are the longest steps within a recipe. The minor steps, such as steps A, C, and E could be treated as transition steps. Moreover, experienced

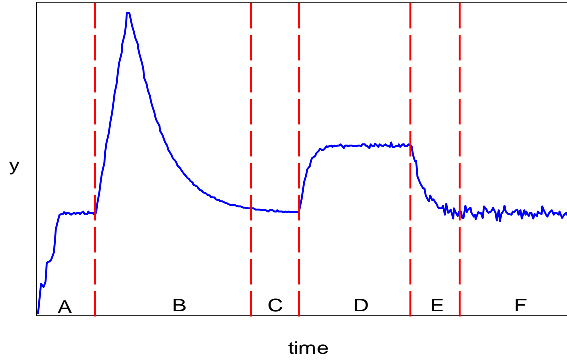


Fig. 2. Schematic of key sensitive time-slot (KST).

engineers can identify critical steps with little difficulty.

Specifications or will give indication on tool condition. The KSV can be classified as:

1. *Variable-based KSV*: This is rather straightforward that the KSV is the process variable itself and it can be directly read from raw data. The KSV can be the variable at certain snapshot such as the initial value, final value, maximum value, and minimum value etc. For example, the peak value in the step B of Fig.2 may be used as a KSV. One should note that raw data may not precisely capture true behavior with a low sampling frequency or fast response processes.
2. *Computed feature-based KSV*: Some computed values from raw measurement, such as slope, mean, standard deviation, may have important physical implications. Again, let us use the step F in Fig.2 to illustrate this. The mean value or standard deviation can be a sensitive measure for process trend. Another possible example is the area of the peak or the ramp up slope in Step B (Fig. 2). This type of KSV, to a degree, reflects some physical meaning, e.g., integrated area for effective energy input.
3. *Regressed feature-based KSV*: Parameters of a prescribed model can be used extract process feature. These quantities can describe process condition as batch progresses. Simple models, steady-state polynomial model or dynamical transfer function model. For example, one could use the initial value, steady state gain, and time constant to capture the behavior of a first order response at the current stage (step D in Fig.2). This is effective for identifying possible variation in process dynamics.

The on-going discussion clearly shows that the introduction of the KST and KSV is actually doing the dimensional reduction for subsequent analyses. In doing this, a two-dimensional data matrix (the number of observation by the number of variables) in a single batch can be reduced to a vector of KSVs. Thus, it will be much easier to incorporate models, steady-state or dynamic model, for monitoring and/or fault detection.

After obtaining candidate KSVs from process knowledge, a certain mechanism is necessary for validation. It is obvious, the intuitively correct KSVs may or may not have strong link to quality spec or to the tool health condition as the batch progresses. The candidate KSVs are sequences of data taken sequentially and it can be viewed as a time series. A straightforward approach is to exclude variables which exhibit the behavior of random variable. In other words, the KSV, to a degree, should be able to capture the process trend as the batch progresses. The autocorrelation is a simple measure to discriminate true KSV from random variables, as far as process trend is concerned. The most satisfactory estimate of the kth lag autocorrelation of a time series is (Box et al., 1994):

$$r_k = \frac{c_k}{c_0} \tag{1}$$

where

$$c_k = \frac{1}{N}\sum_{t=1}^{N-k}(z_t - \bar{z})(z_{t+k} - \bar{z}) \tag{2}$$

(k=0, 1, 2…., k) is the estimate of the autocovariance, and $\bar{z}$ is the sample mean of the time series.

If the autocorrelation function of time series for a candidate is found to be significant, it is then validated. Otherwise, if a weak correlation is observed, it can be treated as a white noise sequence which offers little information on process trend. Thus, some candidate KSVs can be removed after autocorrelation analysis. If, unfortunately, none of the KSVs has significant expression, one should reevaluate KSVs, even KST. Again, it should be emphasized here that obtaining successful KSVs depends on the understanding and experience on process/equipment. However, a rigorous evaluation is critical for validation. The KSVs give more information on process condition than just applying all variables into a black/gray box modeling.

Mix-products constitute a significant portion in semiconductor manufacturing and this type of problem is essential for foundries. Therefore, it is important to account for the product effect in the KSVs such that effective process trned monitoring can be achieved. The product indices could be linewidth, pattern density, material properties, etc. If a KSV shows unusual behaviors such as abrupt change, shifts, and spikes within a trend, very likely, it may be a consequence of product effects. One can verify this effect by analyzing the correlation between KSVs and product indices. To know the selected KSV having product effects is a challenging task, but process knowledge always offers some insight. Tow examples are: the removal rate of CMP differs with linewidth (Chiu et al., 2004) and the geometry of a wafer surface affects the view factor for radiation related processes.

The generalized procedure for obtaining KSVs is given as follow:

S1: Select possible measurements based on experience.
S2: Define the key sensitive time-slots in a recipe.
S3: Obtain possible key sensitive variables.
S4: Check autocorrelation for each KSV. If no significant KSV is found, return to step 2 or 3.
S5: Take out the product effects, if information on product type and corresponding is available.

After this procedure, raw data of a batch process has been reduced into a vector in which each element is a KSV. Therefore, the data-drive analyses such as PCA, PLS and ANN could be applied straightly. In following section, we will propose a method to construct a time series based healthy index from these KSVs

3、Key Sensitive Index

In the case of extreme dimension reduction, a scalar index could be constructed as a function of many KSVs for one batch. This index should reveal the current status or critical feature of a batch trajectory, and it is very convenient for monitoring. This kind of index is termed as key sensitive indices (KSI) here which is used to describe the behavior of process. The choice of KSI may depend on the analysis done on the KSVs aforementioned. The possible ways for constructing KSI are described, but not limited to, as the following.

Variable-based KSI. The KSI is the KSV itself. If only one KSV is found and it exhibits significant autocorrelation, the simplest way is to take this KSV as KSI. The upper and lower limits for the KSI can be established to monitoring the batch process. In addition, the batch process trend can be realized by inspecting the KSI with batch process progressing.

Model-based KSI. The KSI is the prediction residual from time series models of KSVs. For a KSV with significant autocorrelation, it is suggested to identify time series models of this KSV for forecasting its future behavior. When the time series model is built using normal operating data, the difference between its predicted value and actual KSV of a batch can serve as the KSI. A large KSI (i.e. residual) means the process to deviate from its normal operating condition significantly. Moreover, we can identify different kind of time series models (e.g. ARMA and ARIMA) and use them for prediction to check the dynamic behavior (e.g. drifting) of the batch process progressing.

Data-based KSI. The KSI is a statistic (e.g. T2, Q) resulted from model of PCA on KSVs. In some cases, no significant autocorrelation can be found in any possible KSVs computed. Since a batch trajectory is represented by several KSVs, multivariate projection methods such as PCA can be applied on these KSVs for batch process monitoring. Thus, the KSI could be the statistics, T2 or Q, frequently used in PCA monitoring. Such KSI not only can be used for batch process monitoring, but also is suitable for fault diagnoses because it is derived based on PCA.

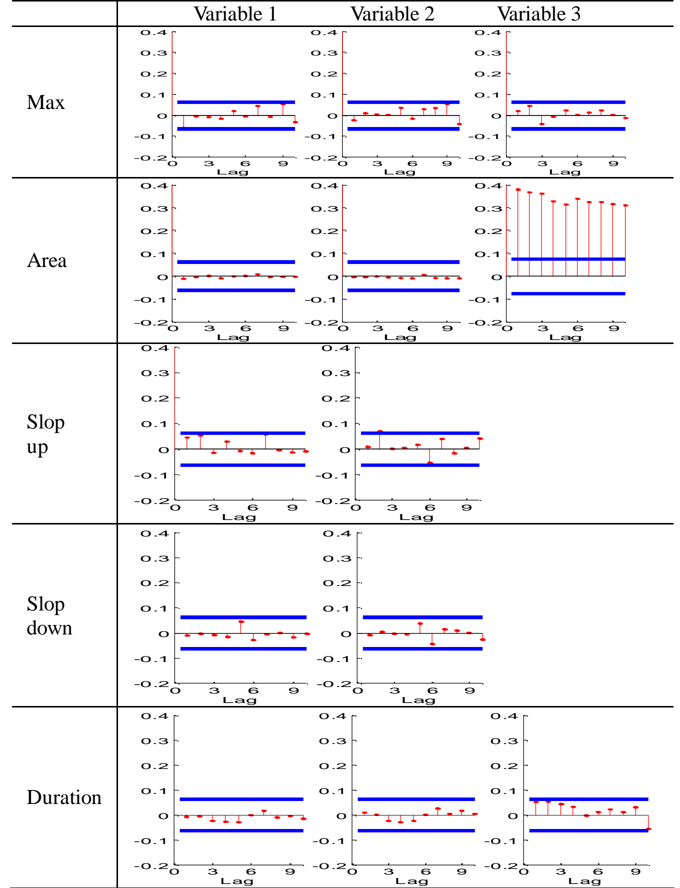
4、Case Study

4.1 Case Study 1- Thermal Process

Filtering KSVs with Product Effects. Here comes a case study for illustration. A PM index is desired for a process tool, and the engineer provides three most important measurements. The autocorrelation analysis of possible KSV candidates is summarized in Table 1. The variable 3 does not have features of slopes, and has the only one significant autocorrelation on maximum value which is termed as $V3_{max}$ as plotted in Fig. 3 (a). As this tool has been proceed with almost five thousand wafers, this window size covers two completed PM cycles which are respectively located at vertical dash lines. Obviously, this KSV follows the PM behavior, because of abrupt shifts just only behind each PM.

The appearance of many spikes in $V3_{max}$ seems not appropriate for any sequential application. The first instinctive reason resulted in these spikes comes out with that there are many different product in a foundry fab. The available information describing different product has been collected as product index 1, 2 and 3 (PI_1, PI_2, and PI_3). Consequently, we check the correlation coefficient between product indices and $V3_{max}$. The result indicates that the combination of PI_1 and PI_2, PI_{1+2}, has the strongest relationship with $V3_{max}$. In Fig.4, the spikes of $V3_{max}$ occur when the product index has higher values. Based on this observation, we do the some modifications including the least square regression, in which, if PI_{1+2} is beyond a threshold value, $V3_{max}$ will be reduced a values: kPI_{1+2}. The threshold value and parameter K are obtained in least square regression. The modified value, $V3'_{max}$, is demonstrated in Fig.3 (b). Therefore, this KSV is much clearer to indicate the PM behavior by taking out product

Table 1 Autocorrelation analysis of possible KSVs in Case Study 1



effects.

A Time Series Based KSI. Roughly, $V3'_{max}$ can be treated as a monitoring index with given upper and lower control limits. However, if the tool's behavior (e.g., health index) can be captured, it is more reliable to make a decision of PM at which timing. The time series analysis (Box et al., 1994) is helpful for modeling autoregressive polynomial is close to unity, which means that the time series of $V3'_{max}$ exhibits nonstationary behavior. For this reason, an autoregressive integrated moving average (ARIMA) model is then built as the following to describe this behavior.

$$\left(1+0.942\,q^{-1}\right)\nabla V3'_{max}(t)=\left(1+0.452\,q^{-1}-0.553\,q^{-2}\right)e(t) \quad (4)$$

where $\nabla=(1-q^{-1})$. These two time-series models are then been used for forecasting the values of $V3'_{max}$ as the batch process progresses. Initially, both the forecasts of ARMA and ARIMA models can follow the process trend well. However, as the batch process progresses, the forecast of ARMA model starts to deviate from the actual $V3'_{max}$ more and more, while the forecast of ARIMA model keeps following. This phenomenon disappears after PM and then can be observed again as the batch process progresses. In order to capture the drifting behavior of this batch process, the KSI is thus defined as the absolute value of difference between residuals of these two models.

$$KSI = |\,Residual_{ARMA} - Residual_{ARIMA}\,| \quad (5)$$

The computed KSI is shown in Fig. 5. The results clearly indicate that the process trend can be realized using the proposed KSI and tool maintenance is required once this KSI is greater than a prescribed limit. Therefore, this

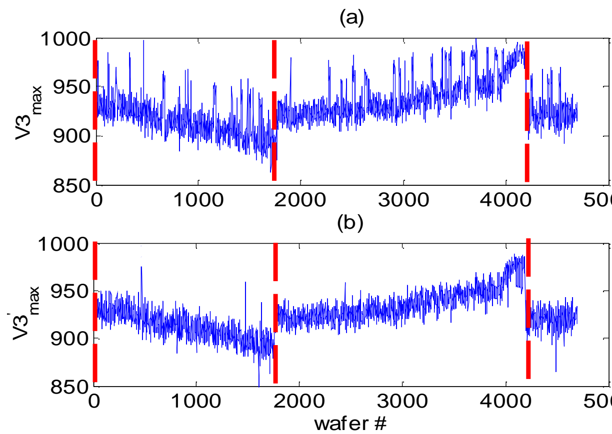


Fig. 3. The Trend of (a) KSV and (b) modified KSV in case study 1

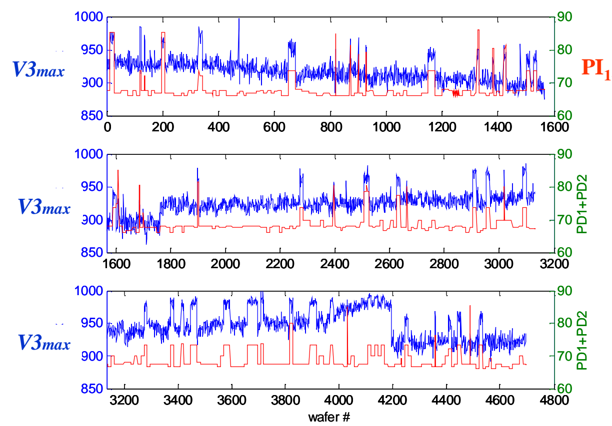


Fig. 4. The influence of product index in case study 1

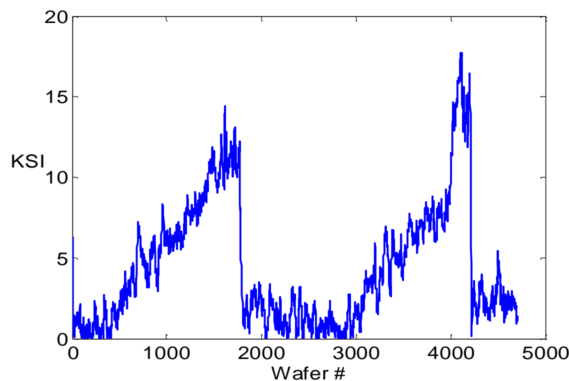


Fig. 5. The resultant key sensitive index (KSI) for case study 1

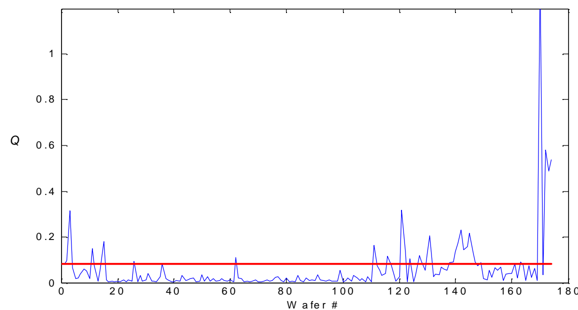


Fig. 6. Fault detection of case study 2

KSI-based approach not only can be used for batch process trend monitoring, but also it is helpful for the engineers to decide when to call for tool maintenance.

4.1 Case Study 2- Thin Film Process

The concept of KSV is also been applied to another thin film process tool. There are three issues in this case study. One is virtual metrology which relates tool raw data and quality index, and the other two are fault detection and process trend monitoring.

The engineers provide totally 23 variables raw data. After filtering out some constant, meaningless, and poor resolution variables, we attempt to obtain KSVs from two key sensitive time-slots. Because the data of quality is given, we search many numbers of KSV to match quality as possible. Applying the least square model obtained from the training set to predict the test set, the accuracy is R^2=0.65 in which 41 KSVs are used. Although, this result may not be outstanding, it's value comes from that the simple concept of KSV and simple least square modeling can hit the greater part of quality behavior.

Besides, this process tool may produce defects that will no be detected until several sequential process steps have been proceed. A period of tool raw data that contains several scrapped wafers is provided. We obtain 16 KSVs, including wafer temperature, chamber side temperature, and other variables. A PCA model is built based on normal (no defects) wafers, and consequently use Q statistic for detection as shown in Fig. 6. At the end of Q line, the last 4 wafers soar abnormally, and these wafers have also been classified as scrapped wafers. For diagnosis, the contribution analysis shows several significant weighting KSVs which are obtained from chamber temperature. According to the process engineer, there was a leakage on a gas tube at that time, and it resulted in chamber side temperature increasing abnormally. It is coincident with our contribution analysis. Hence, the concept also can be applied to fault detection and diagnosis successfully.

Finally, for process trend monitoring, we also use 16 KSVs as described previously. This KSI grows up with the progress of batch process and return to its normal value immediately after PM. The results again indicate that the process trend and the healthy condition of the tool can be realized using the proposed KSI.

5、Conclusion

The concept of using KSV to construct a KSI is easy and straightforward, but with great benefit. It captures the key features of measurements for consequential analyses without complicated data pre-processing. We have demonstrated two successful real cases by proposed method. On the contrary, simplification also could possible lose some important information. The understanding of processes and equipment make KSV or other analysis technique working out.

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參加美國化工年會 (AIChE Annual Meeting) 報告

余政靖
國立台灣大學化工系

一. 參加會議經過

美國 2006 化工年會在 San Francisco, California 舉行，這是化工界相當重要的學術會議，因為化工各領域的研究主流大都會參予，因為在舊金山舉行參加人數都在 5000 人左右。 此會提供相當好的機會了解同領域研究者的方向及進展以及新的研究走向，這是一個值得認真參與的會議。 我們在會中有兩篇口頭報告及一篇壁報論文，口頭報告中一篇由學生報告而另外一篇由我報告。主題分別是:

1. Tung, S. T.; Yu, C. C. "Effects of Relative Volatility Ranking to the Design of Reactive Distillation", AIChE Annual Meeting, Nov. 12- 17, San Francisco, paper 674c, **2006.**
2. Lin, Y. D.; Chen, J. H.; Huang, H. P.; Yu, C. C. "Process Alternative for Methyl Acetate Conversion Using Reactive Distillation: Transesterification Versus Hydrolysis", AIChE Annual Meeting, Nov. 12- 17, San Francisco , paper 303k, **2006.**
3. Jeng, J. C.; Su, A. J.; Huang, H. P.; Yu, C. C. "Process Trend Monitoring Based on Key Sensitive Index: Applications Semiconductor Manufacturing", AIChE Annual Meeting, Nov. 12- 17, San Francisco, paper 92a, **2006.**

台灣的參與者除了我以外還有台科大，台大，中央，長庚，成大的師生以及亞洲同領域來自韓國，日本，新加坡及中國的學者。雖然會場分布相當廣，但同領域的發表還是至於鄰近區域，也是個 meet old friend and know new friends 的好場合。

二. 與會心得

這次會議中，本人參與此活動的進行，除了了解各國相關研究者對於各種題目的研究情形，也在更宏觀的了解化工程序系統設計與控制的架構，這對未來研究方向及構想皆有助益。整體來說，個人認為參加這種會議，能有較深入的討論收穫良多，更了解國際上研究趨勢，並與他國學者交換彼此研究的心得。這在未來研究規劃上相當有幫助。

三. 攜回資料

會議手冊。

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參加美國化工年會 (AIChE Annual Meeting) 報告

余政靖
國立台灣大學化工系

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